

IN THE CLAIMS:

Claims 18 through 173 were previously cancelled. None of the claims have been amended herein. All of the pending claims 1 through 17 are presented below for convenience of the Examiner. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as previously amended.

1. (Previously presented) A card comprising:
a substrate formed from a strip of a plurality of substrates including a first side having a plurality of conductors, a second side having a plurality of contacts connected to at least one conductor of the plurality of conductors on the first side, at least one encapsulated semiconductor component on the first side, a molded peripheral portion laterally outwardly forming a periphery of the substrate, and at least one exposed connecting segment exposed at one of the periphery of the substrate and an intermediate region of the periphery of the substrate.
2. (Original) The card of claim 1, further comprising a notch in the periphery of the substrate to recess a portion of the exposed at least one connecting segment to a nonprotruding position.
3. (Previously presented) The card of claim 1, wherein a portion of the at least one encapsulated semiconductor component abuts a portion of the molded peripheral portion along an interface thereof.
4. (Previously presented) The card of claim 3, wherein an abutting portion of the molded peripheral portion is coplanar with the portion of the at least one encapsulated semiconductor component.

5. (Previously presented) The card of claim 1, wherein encapsulation material of the at least one encapsulated semiconductor component and molding material of the molded peripheral portion comprise epoxy resin.

6. (Original) The card of claim 1, wherein the substrate comprises a reinforced organic polymer resin.

7. (Original) The card of claim 1, wherein the second side of the substrate is substantially exposed.

8. (Original) The card of claim 1, wherein the at least one semiconductor component comprises a memory component.

9. (Original) The card of claim 1, wherein the card comprises a memory card for digitally recording and retrievably storing photographic data in a digital camera.

10. (Previously presented) A card comprising:
a printed circuit substrate formed from a strip of a plurality of substrates including a first side having a plurality of conductors, a second side having a plurality of contacts connected to at least one conductor of the plurality of conductors on the first side, at least one encapsulated semiconductor component on the first side, a molded peripheral portion laterally outwardly forming a periphery of the substrate, and at least one exposed connecting segment exposed at one of the periphery of the substrate and an intermediate region of the periphery of the substrate.

11. (Previously presented) The card of claim 10, further comprising a notch in the periphery of the printed circuit substrate to recess a portion of the at least one exposed connecting segment to a nonprotruding position.

12. (Previously presented) The card of claim 10, wherein a portion of the at least one encapsulated semiconductor component abuts a portion of the molded peripheral portion along an interface thereof.

13. (Previously presented) The card of claim 12, wherein an abutting portion of the molded peripheral portion is substantially coplanar with the portion of the at least one encapsulated semiconductor component.

14. (Original) The card of claim 10, wherein the printed circuit substrate comprises a reinforced organic polymer resin.

15. (Original) The card of claim 10, wherein the second side of the printed circuit substrate is substantially exposed.

16. (Original) The card of claim 10, wherein the at least one semiconductor component comprises a memory component.

17. (Previously presented) The card of claim 10, wherein the card comprises a memory card for digitally recording and retrievably storing photographic data in a digital camera.

18.-173. (Cancelled)